L	Hits	Search Text	DB	Time stamp
Numb r	0	conduct\$3 adj assemb\$3 near solderless	USPAT;	2004/02/26
•	•		US-P PUB;	08:29
			EP ; JP ;	
			DERWENT;	
			IBM_TDB	
2	62	conduct\$3 near solderless	USPAT;	2004/02/26
_			US-PGPUB;	08:30
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
3	29	conduct\$3 near assembly and spring near	USPAT;	2004/02/26
		force and hook	US-PGPUB;	08:32
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
<u>a</u>	a 291	conduct\$3 near assembly and spring near	USPAT;	2004/02/26
· .	W	force	US-PGPUB;	08:33
10	9	10100	EPO; JPO;	
Clar Man	,		DERWENT;	
3			IBM_TDB	
5	923	439/79.ccis.	USPAT;	2004/02/26
	323	403/13:0013:	US-PGPUB;	08:33
			EPO; JPO;	00.00
r			DERWENT;	
			IBM_TDB	
6	21	439/79.ccis. and solderless	USPAT;	2004/02/26
	21	455/15/CCIS: AIM SOIDERIESS	US-PGPUB;	08:36
			EPO; JPO;	00.00
			DERWENT;	
			IBM_TDB	
_	3	contact near assembly and solderless and	USPAT;	2004/02/26
7 .	3	(439/79; 439/108 ; 439/101 ; 439/701 ;	US-PGPUB;	08:49
		439/247).ccls.	EPO; JPO;	JU:43
		TOTIENT J.CCIS.	DERWENT:	
			IBM TDB	
8	14	("3444502" "3744009" "3794953"	USPAT	2004/02/26
0	14	"3842189" "3883207" "3885848"	USFAI	08:37
		"4113342" "4186988" "4262981"		00.37
		• • • • • • • • • • • • • • • • • • • •		
		"4286835" "4296991" "4386815" "4422128" "4457570").PN.		
_		,	USPAT	2004/02/26
9	6	("2905921" "3771101" "3865454"	USFAI	
40	_	"3868166" "3871728" "4089581").PN.	HERAT	08:39
10	7	4089581.URPN.	USPAT	2004/02/26
		(10.40-10-10-10-10-10-10-10-10-10-10-10-10-10		08:40
11	10	("3137537" "3848221" "3899234"	USPAT	2004/02/26
		"4068170" "4089581" "4279459"		08:41
		"4288140" "4357066" "4428635"		
	l .	"4431252").PN.	1	I

12	3	c ntact near assembly and solderless and (439/265, 29/832, 439/260, 439/266, 439/267, 439/325 339/74R; 339/75M; 339/75MP; 339/176MP; 29/832; 29/834; 29/842;439/79; 439/108; 439/101; 439/701; 439/247).ccls.	USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB	2004/02/26 08:50
13	8	creighton near david .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 08:51
14	2	creighton near david .inv. and assembly	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 09:33
15	1946	29/739.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 09:34
16	7	29/739.ccls. and contact near assembly	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/02/26 09:34
17	15	29/832-836.ccls. and contact near assembly	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/02/26 09:36
18	43	contact near assembly and (29/832, 257/E23.065 , 257/E23.066 , 257/E23.07 , 257/E23.124 , 29/827 , 29/840 , 29/844).ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:38
19	180	contact near assembly and (439/140; 439/374; 439/79; 439/248; 439/271; 439/609; 29/874; 29/882; 29/840; 361/403; 361/409; 361/410; 264/272.14; 264/272.17).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:38
20	3	contact near assembly and solderless and (439/140; 439/374; 439/79; 439/248; 439/271; 439/609; 29/874; 29/882; 29/840; 361/403; 361/409; 361/410; 264/272.14; 264/272.17).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/02/26 09:38

21	7	spring adj contact near assembly and (439/140; 439/374; 439/79; 439/248; 439/271; 439/609; 29/874; 29/882; 29/840; 361/403; 361/409; 361/410; 264/272.14; 264/272.17).ccls.	USPAT; US-P PUB; EP ; JP ; DERWENT; IBM_TDB	2004/02/26 09:39

	Titl	Curr nt OR	Curr nt XR f
	ular plug with	439/59	439/347; 439/507; 439/629; 439/676
	Push- n t rminal clip and assembly	361/776	174/261; 174/267; 361/772; 439/81; 439/83
\top	C nn ct rassembly for mounting a m dul na circuit board or the like	439/81	29/830; 439/259; 439/65
	El ctrical connector receptacle	439/676	379/442; 439/82
	Modular t lephone connector	439/395	439/493; 439/76.1
	Printed circuit board connector	439/62	439/634
	El ctrical connector receptacles	439/676	439/75
	C nduct r arrangement and assembly m th d	439/630	439/68; 968/881; 968/DIG.1
	and met	439/841	
Ì	Low ins rtion force connector for modular	439/264	439/746

	Titl	Curr nt OR	Curr nt XR f
7	CONTACT ARRAY AND METHOD OF MAKING THE SAME	174/52.3	136/213; 174/52.4; 257/712; 257/723; 257/785; 257/786; 361/776; 439/66
12	ELECTRICAL TERMINAL FOR CONDUCTIVE FOIL	439/329	174/117A; 174/267; 439/371; 439/571; 439/801; 439/917
13	PCB SURFACE CONNECTOR	439/329	439/345; 439/557
14	MEANS FOR MAKING AN ELECTRICAL CONNECTION BETWEEN AN ELECTRICAL COMPONENT AND A PRINTED CIRCUIT	439/81	439/329; 439/621

9		Titl	Curr nt OR	R Curr nt XR	4
	Electri n	mponent insertion apparatus	29/33M	29/739; 29/741	
~	Aut matic test system	est system	324/754	29/739	
•	D vic f r ii ard	f r inserting contacts on a support	29/739	29/235; 29/747; 29/844; 29/881	
	S If-masking : circuit boards	S If-masking socket pin carrier for printed circuit boards	29/739	228/180.1; 228/49.5; 228/58; 29/843; 414/736; 439/83; 439/877	
	M thod for a connector	M thod for assembly of electrical connector	29/884	29/739	
	M th dfr! electrical in	M th df r mounting lead sockets to an electrical interconnection board	29/844	29/525; 29/739; 29/743	,
	METHOD AND AI ASSEMBLY OF C CIRCUIT BOARD	PPARATUS FOR ONTACTS IN A PRINTED	29/843	29/739	

L	Hits	Search Text	DB	Time stamp
Number				
1	2	6625881.pn.	USPAT;	2004/02/26
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	* ·		EP ; JP ;	•
			DERWENT;	
			IBM_TDB	-
2	20	("4867696" "4890199" "5053926"	USPAT	2004/02/26
		"5129832" "5188534" "5239127"		10:33
		"5366380" "5373101" "5595490"		
		"5617866" "5639263" "5641314"		
		"5748455" "5820549" "5896107"		
		"5967800" "5991165" "6025806"		
		"6142802" "6200171").PN.		
3	38	("3550062" "3815077" "3873173"	USPAT	2004/02/26
		"3960424" "3993384" "4035046"		10:36
		"4050755" "4052118" "4057311"		
		"4093330" "4176895" "4188085"		
		"4220383" "4268102" "4341433"		
		"4359252" "4494807" "4511201"		
		"4553192" "4660920" "4664458"		
		"4806104" "4927369" "4995814"		
		"4998886" "5041016" "5052943"		
		"5199889" "5226826" "5230632"		
		"5234353" "5259769" "5306163"		
		"5308252" "5310352" "5378160"		
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		"5129832" "5188534" "5239127"		10:41
		"5366380" "5373101" "5595490"		
		"5617866" "5639263" "5641314"		
		"5748455" "5820549" "5896107"		
		"5967800" "5991165" "6025806"		
		"6142802" "6200171").PN.		
5	38	("3550062" "3815077" "3873173"	USPAT	2004/02/26
		"3960424" "3993384" "4035046"	ooi Ai	10:43
		"4050755" "4052118" "4057311"		10.43
		"4093330" "4176895" "4188085"		
		"4220383" "4268102" "4341433"		
		"4359252" "4494807" "4511201"		
		"4553192" "4660920" "4664458"		
		"4806104" "4927369" "4995814"		
		"4998886" "5041016" "5052943"		
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		"5199889" "5226826" "5230632" "5234353" "5259769" "5306163"		
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		"5308252" "5310352" "5378160"		
e l	-	"5584713" "5586890").PN.	110000	0004/00/00
6	7	("4527848" "4857001" "4891019"	USPAT	2004/02/26
		"5002495" "5055054" "5104326"		10:44
_	_	"5161985").PN.		
7	5	("3736471" "3905670" "3960424"	USPAT	2004/02/26
		"4330163" "4350403").PN.		10:45

8	3	("3558154" "3960424" "4664458").PN.	USPAT	2004/02/26
				10:47
9	21	Ammar near Danny.inv.	USPAT;	2004/02/26
			US-P PUB;	10:48
			EP ; JP ;	
			DERWENT;	
			IBM_TDB	
10	2	5188534.pn.	USPAT;	2004/02/26
			US-PGPUB;	10:55
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
11	2	5378160.pn.	USPAT;	2004/02/26
			US-PGPUB;	10:56
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
12	24	("3715706" "3795037" "4161346"	USPAT	2004/02/26
		"4199209" "4295700" "4505529"		10:56
		"4511196" "4738625" "4806104"		10,00
		"4813129" "4927569" "4983126"		
		"4998886" "5061192" "5069627"		
		"5139427" "5147207" "5152695"		
		"5160268" "5173055" "5199889"		
		"5220270" "5228861" "5259777").PN.		
13	20	("3917372" "4236667" "4288140"	USPAT	2004/02/26
		"4575703" "4717817" "4724310"	00.4.	10:58
		"4734567" "4735578" "4752234"		10.00
		"4770639" "4795897" "4799891"		
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		"4932889" "4971568" "4975086"		
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14	4	("3795888" "4084847" "4530557"	USPAT	2004/02/26
		"4900273").PN.		11:00
-	0	conduct\$3 adj assemb\$3 near solderless	USPAT;	2004/02/26
			US-PGPUB;	10:32
			EPO; JPO;	-
			DERWENT;	
			IBM_TDB	
-	62	conduct\$3 near solderless	USPAT;	2004/02/26
			US-PGPUB;	08:30
			EPO; JPO;	- 3.00
			DERWENT;	
			IBM_TDB	
-	29	conduct\$3 near assembly and spring near	USPAT;	2004/02/26
		force and hook	US-PGPUB;	08:32
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
L	I		I I I I I I I I I I I I I I I I I I I	

•	291	c uct\$3 near assembly and spring near	USPAT;	2004/02/26
		force	US-PGPUB;	08:33
			EP ; JP ;	
			DERWENT;	
			IBM_TDB	
-	923	439/79.ccls.	USPAT;	2004/02/26
			US-PGPUB;	08:33
			EPO; JPO;	00.33
			DERWENT;	
			IBM_TDB	
_	21	439/79.ccls. and solderless	USPAT;	2004/02/20
		4007 0100131 and solderless	•	2004/02/26
			US-PGPUB;	08:36
			EPO; JPO;	
			DERWENT;	
_	3		IBM_TDB	
•	3	contact near assembly and solderless and	USPAT;	2004/02/26
		(439/79; 439/108 ; 439/101 ; 439/701 ;	US-PGPUB;	08:49
		439/247).ccls.	EPO; JPO;	
			DERWENT;	
	4.4		IBM_TDB	
,	14	("3444502" "3744009" "3794953"	USPAT	2004/02/26
		"3842189" "3883207" "3885848"		08:37
		"4113342" "4186988" "4262981"		
		"4286835" "4296991" "4386815"		
		"4422128" "4457570").PN.		
1	6	("2905921" "3771101" "3865454"	USPAT	2004/02/26
		"3868166" "3871728" "4089581").PN.		08:39
•	7	4089581.URPN.	USPAT	2004/02/26
				08:40
•	10	("3137537" "3848221" "3899234"	USPAT	2004/02/26
		"4068170" "4089581" "4279459"		08:41
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	3	contact near assembly and solderless and	USPAT;	2004/02/26
		(439/265, 29/832 , 439/260 , 439/266 ,	US-PGPUB;	08:50
		439/267 , 439/325 339/74R; 339/75M;	EPO; JPO;	-
		339/75MP; 339/176MP; 29/832; 29/834;	DERWENT;	
		29/842;439/79; 439/108 ; 439/101 ; 439/701 ;	IBM_TDB	
		439/247).ccls.		
		•		
	8	creighton near david .inv.	USPAT;	2004/02/26
			US-PGPUB;	08:51
			EPO; JPO;	
			DERWENT;	
	2	avaighten near deadd in	IBM_TDB	
	2	creighton near david .inv. and assembly	USPAT;	2004/02/26
		·	US-PGPUB;	09:33
		·	EPO; JPO;	
	[DERWENT;	
			IBM_TDB	

-	1946	2539.ccls.	USPAT;	2004/02/26
			US-P PUB;	09:34
			EP ; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	29/739.ccls. and c ntact near assembly	USPAT;	2004/02/26
			US-P PUB;	09:34
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	15	29/832-836.ccls. and contact near assembly	USPAT;	2004/02/26
			US-PGPUB;	09:36
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	43	contact near assembly and (29/832,	USPAT;	2004/02/26
		257/E23.065 , 257/E23.066 , 257/E23.07 ,	US-PGPUB;	09:38
		257/E23.124	EPO; JPO;	
		, 29/827 , 29/840 , 29/844).ccls.	DERWENT;	
		, 20/04/ , 20/040 , 20/04///00/01	IBM_TDB	
		*	.5m_155	
_	180	contact near assembly and (439/140;	USPAT;	2004/02/26
		439/374 ; 439/79 ; 439/248 ; 439/271 ;	US-PGPUB;	09:38
		439/609; 29/874; 29/882; 29/840; 361/403;	EPO; JPO;	03.30
		361/409 ; 361/410 ; 264/272.14 ;	DERWENT;	
		264/272.17).ccis.	IBM_TDB	
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-	3	contact near assembly and solderless and	USPAT;	2004/02/26
		(439/140; 439/374 ; 439/79 ; 439/248 ;	US-PGPUB;	09:38
		439/271 ; 439/609; 29/874 ; 29/882 ; 29/840 ;	EPO; JPO;	75100
		361/403 ; 361/409 ; 361/410 ; 264/272.14 ;	DERWENT;	
		264/272.17).ccls.	IBM_TDB	
		EUTE EIT JUUISI	.DM_100	
_	7	spring adj contact near assembly and	USPAT;	2004/02/26
•	'	(439/140; 439/374 ; 439/79 ; 439/248 ;	US-PGPUB;	09:39
		439/271 ; 439/609; 29/874 ; 29/882 ; 29/840 ;	EPO; JPO;	
		361/403 ; 361/409 ; 361/410 ; 264/272.14 ;		
		264/272.17).ccls.	DERWENT;	
		20-11 2. I 1 j. GG15.	IBM_TDB	
		*		
			L	<u> </u>